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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

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Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I <sup>2</sup> C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64mc506t-e-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

# TABLE 2: dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X MOTOR CONTROL FAMILIES (CONTINUED)

			(00																		
	<i>•</i>	(se			-	Re	mappa	ble P	eriphe	erals					~						
Device	Page Erase Size (Instructions)	Program Flash Memory (Kbytes)	RAM (Kbytes)	16-Bit/32-Bit Timers	Input Capture	Output Compare	Motor Control PWM <sup>(4)</sup> (Channels)	Quadrature Encoder Interface	UART	SPI <sup>(2)</sup>	ECAN™ Technology	External Interrupts <sup>(3)</sup>	I <sup>2</sup> C <sup>TM</sup>	<b>CRC Generator</b>	10-Bit/12-Bit ADC (Channels)	Op Amps/Comparators	CTMU	ЪТG	I/O Pins	Pins	Packages
dsPIC33EP32MC504	512	32	4																		
dsPIC33EP64MC504	1024	64	8																		VTLA <sup>(5)</sup> ,
dsPIC33EP128MC504	1024	128	16	5	4	4	6	1	2	2	1	3	2	1	9	3/4	Yes	Yes	35	44/ 48	TQFP, QFN,
dsPIC33EP256MC504	1024	256	32																	40	UQFN
dsPIC33EP512MC504	1024	512	48																		
dsPIC33EP64MC506	1024	64	8																		
dsPIC33EP128MC506	1024	128	16	5	4	4	6	1	2	2	1	3	2	1	16	3/4	Voo	Voo	53	64	TQFP,
dsPIC33EP256MC506	1024	256	32	3	4	4	0	1	2	2	1	3	2	1	10	3/4	Yes	Yes	55	04	QFN
dsPIC33EP512MC506	1024	512	48																		

 Note 1:
 On 28-pin devices, Comparator 4 does not have external connections. Refer to Section 25.0 "Op Amp/Comparator Module" for details.

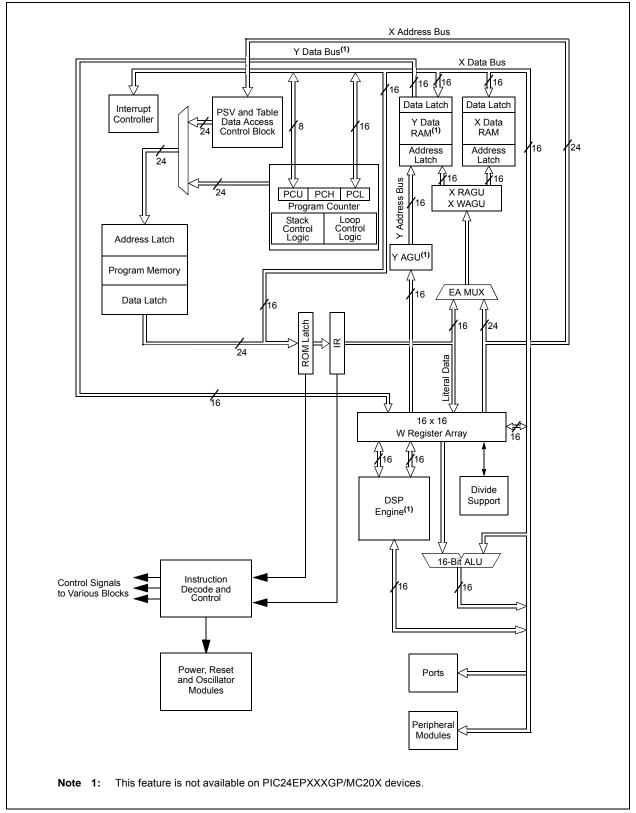
 2:
 Only SPI2 is remappable.

3: INT0 is not remappable.

4: Only the PWM Faults are remappable.

5: The SSOP and VTLA packages are not available for devices with 512 Kbytes of memory.

FIGURE 3-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X CPU BLOCK DIAGRAM



IABLE 4	-10.	001		JMPARE			OUIFU		ARE 4	REGIS		<u>٢</u>						
File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1CON1	0900	—	-	OCSIDL	C	CTSEL<2:0	)>	—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE		OCM<2:0>		0000
OC1CON2	0902	FLTMD	FLTOUT	FLTTRIEN	OCINV	_	_	_	OC32	OCTRIG	TRIGSTAT	OCTRIS		SYN	NCSEL<4:0	>		000C
OC1RS	0904							Outp	out Compare	e 1 Seconda	ary Register							xxxx
OC1R	0906								Output Co	mpare 1 Re	gister							xxxx
OC1TMR	0908								Timer V	alue 1 Regi	ster							xxxx
OC2CON1	090A	_	—	OCSIDL	0	CTSEL<2:0	)>	_	ENFLTB	ENFLTA	_	OCFLTB	OCFLTA	TRIGMODE		OCM<2:0>		0000
OC2CON2	090C	FLTMD	FLTOUT	FLTTRIEN	OCINV	_	_	_	OC32	OCTRIG	TRIGSTAT	OCTRIS		SYN	NCSEL<4:0	>		000C
OC2RS	090E		Output Compare 2 Secondary Register									xxxx						
OC2R	0910								Output Co	mpare 2 Re	gister							xxxx
OC2TMR	0912								Timer V	alue 2 Regi	ster							xxxx
OC3CON1	0914	_	—	OCSIDL	0	CTSEL<2:0	)>	_	ENFLTB	ENFLTA	_	OCFLTB	OCFLTA	TRIGMODE		OCM<2:0>		0000
OC3CON2	0916	FLTMD	FLTOUT	FLTTRIEN	OCINV	_	_	_	OC32	OCTRIG	TRIGSTAT	OCTRIS		SYN	NCSEL<4:0	>		000C
OC3RS	0918							Outp	out Compare	e 3 Seconda	ary Register							xxxx
OC3R	091A								Output Co	mpare 3 Re	gister							xxxx
OC3TMR	091C								Timer V	alue 3 Regi	ster							xxxx
OC4CON1	091E	_	—	OCSIDL	0	CTSEL<2:0	)>	_	ENFLTB	ENFLTA	_	OCFLTB	OCFLTA	TRIGMODE		OCM<2:0>		0000
OC4CON2	0920	FLTMD	FLTOUT	FLTTRIEN	OCINV	_	_	_	OC32	OCTRIG	TRIGSTAT	OCTRIS		SYN	NCSEL<4:0	>		000C
OC4RS	0922							Outp	out Compare	e 4 Seconda	ary Register							xxxx
OC4R	0924								Output Co	mpare 4 Re	gister							xxxx
OC4TMR	0926	26 Timer Value 4 Register x							xxxx									

## TABLE 4-10: OUTPUT COMPARE 1 THROUGH OUTPUT COMPARE 4 REGISTER MAP

Legend: x = unknown value on Reset, - = unimplemented, read as '0'. Reset values are shown in hexadecimal.

## 8.0 DIRECT MEMORY ACCESS (DMA)

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Direct Memory Access (DMA)" (DS70348) in the "dsPIC33/ PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
  - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The DMA Controller transfers data between Peripheral Data registers and Data Space SRAM

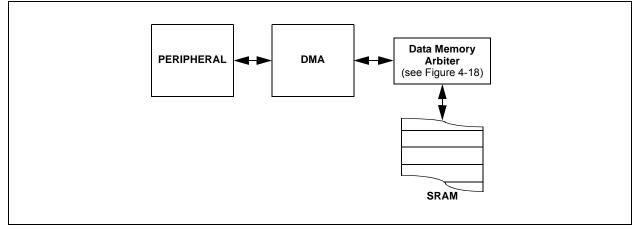
In addition, DMA can access the entire data memory space. The Data Memory Bus Arbiter is utilized when either the CPU or DMA attempts to access SRAM, resulting in potential DMA or CPU stalls.

The DMA Controller supports 4 independent channels. Each channel can be configured for transfers to or from selected peripherals. Some of the peripherals supported by the DMA Controller include:

- ECAN<sup>™</sup>
- Analog-to-Digital Converter (ADC)
- Serial Peripheral Interface (SPI)
- UART
- Input Capture
- Output Compare

Refer to Table 8-1 for a complete list of supported peripherals.

## FIGURE 8-1: DMA CONTROLLER MODULE



- g) The TRISx registers control only the digital I/O output buffer. Any other dedicated or remappable active "output" will automatically override the TRIS setting. The TRISx register does not control the digital logic "input" buffer. Remappable digital "inputs" do not automatically override TRIS settings, which means that the TRISx bit must be set to input for pins with only remappable input function(s) assigned
- h) All analog pins are enabled by default after any Reset and the corresponding digital input buffer on the pin has been disabled. Only the Analog Pin Select registers control the digital input buffer, *not* the TRISx register. The user must disable the analog function on a pin using the Analog Pin Select registers in order to use any "digital input(s)" on a corresponding pin, no exceptions.

#### 11.6 I/O Ports Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser:
	http://www.microchip.com/wwwproducts/ Devices.aspx?dDocName=en555464

#### 11.6.1 KEY RESOURCES

- "I/O Ports" (DS70598) in the "dsPIC33/PIC24 Family Reference Manual"
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- Development Tools

#### REGISTER 11-16: RPINR38: PERIPHERAL PIN SELECT INPUT REGISTER 38 (dsPIC33EPXXXMC20X AND PIC24EPXXXMC20X DEVICES ONLY)

	-					-	
U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
				DTCMP1R<6:	0>		
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	_		_	—	—
bit 7							bit C
Legend:							
R = Readal	R = Readable bit W = Writable bit				mented bit, read	d as '0'	
-n = Value a	at POR	'1' = Bit is set	:	'0' = Bit is cle	x = Bit is unkr	nown	
bit 15	Unimpleme	nted: Read as '	0'				
bit 14-8		6:0>: Assign PV 1-2 for input pin		•	on Input 1 to the	e Corresponding	g RPn Pin bits
	1111001 =	Input tied to RP	1121				
	•						
	•						
		Input tied to CM	P1				
		Input tied to Vss					
bit 7-0		nted: Read as '					
			-				

## 18.0 SERIAL PERIPHERAL INTERFACE (SPI)

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Serial Peripheral Interface (SPI)" (DS70569) in the "dsPIC33/PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
  - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with Motorola<sup>®</sup> SPI and SIOP interfaces.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X device family offers two SPI modules on a single device. These modules, which are designated as SPI1 and SPI2, are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

Note: In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 and SPI2 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 module takes advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of the SPI2 module, but results in a lower maximum speed for SPI2. See **Section 30.0** "**Electrical Characteristics**" for more information.

The SPIx serial interface consists of four pins, as follows:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- SSx/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, SSx is not used. In 2-pin mode, neither SDOx nor SSx is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0				
FRMEN	SPIFSD	FRMPOL	—	—	_	—	_				
bit 15							bit 8				
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0				
_	—	—	_		_	FRMDLY	SPIBEN				
bit 7							bit 0				
Legend:											
R = Readable	e bit	W = Writable b	pit	U = Unimpler	nented bit, rea	ad as '0'					
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown				
bit 15	FRMEN: Fra	med SPIx Suppo	ort bit								
		SPIx support is e SPIx support is d		x pin is used as	Frame Sync	oulse input/outpu	it)				
bit 14	SPIFSD: Fra	me Sync Pulse [	Direction Co	ontrol bit							
		ync pulse input ( ync pulse output									
bit 13	FRMPOL: Fr	ame Sync Pulse	Polarity bit	t							
		ync pulse is activ	•								
		ync pulse is activ									
bit 12-2	-	nted: Read as '0									
bit 1		ame Sync Pulse	-								
		ync pulse coincio ync pulse preceo									
bit 0	SPIBEN: Enhanced Buffer Enable bit										
		d buffer is enable									
	0 = Enhance	d buffer is disabl	ed (Standa	rd mode)							

#### REGISTER 18-3: SPIXCON2: SPIX CONTROL REGISTER 2

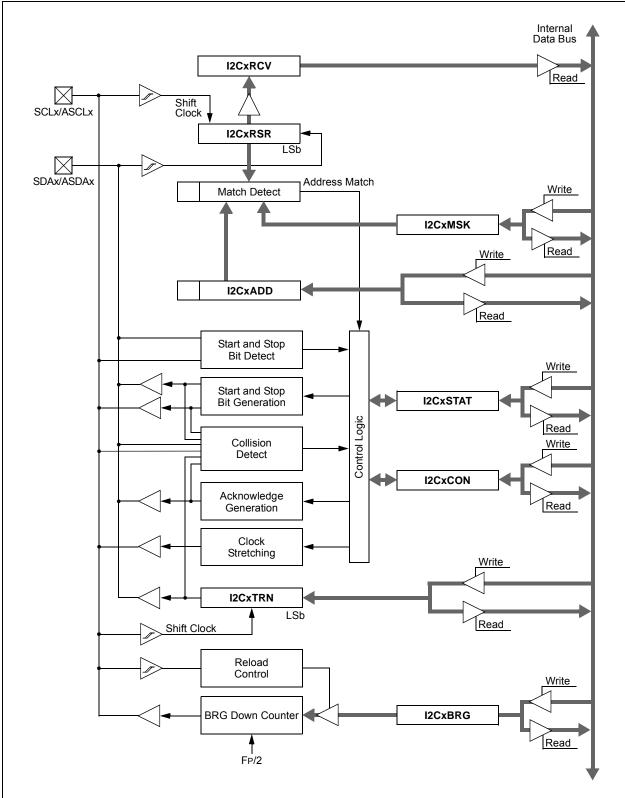


FIGURE 19-1: I2Cx BLOCK DIAGRAM (X = 1 OR 2)

#### 21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

#### BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x		
	—	_	SID10	SID9	SID8	SID7	SID6		
bit 15							bit 8		
R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x		
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE		
bit 7							bit 0		
Legend:									
R = Readabl	e bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'			
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cleared x = Bit is unknown					
bit 15-13	Unimplemen	ted: Read as '	כי						
bit 12-2	<b>SID&lt;10:0&gt;:</b> S	Standard Identifi	ier bits						
bit 1	SRR: Substitu	ute Remote Re	quest bit						
	When IDE =	0:							
	1 = Message	will request rer	note transmis	ssion					
	0 = Normal m	nessage							
	When IDE = 1	<u>1:</u>							
	The SRR bit r	must be set to '	1'.						
bit 0	IDE: Extende	d Identifier bit							
	1 = Message	will transmit Ex	tended Ident	ifier					
	0 = Message	will transmit St	andard Identi	fier					

#### BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x			
—	—	—	_	EID17	EID16	EID15	EID14			
bit 15							bit 8			
R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x			
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6			
bit 7							bit 0			
Legend:										
R = Readable	R = Readable bit W = Writable bit				U = Unimplemented bit, read as '0'					
-n = Value at POR '1' = Bit is set				'0' = Bit is cle	ared	x = Bit is unkr	nown			

bit 15-12 Unimplemented: Read as '0'

bit 11-0 EID<17:6>: Extended Identifier bits

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0			
—	_	—		—	_	—	ADDMAEN			
bit 15							bit 8			
U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0			
0-0	0-0	0-0	0-0	0-0			-			
	—	—	_	—	DMABL2	DMABL1	DMABL0			
bit 7							bit 0			
Legend:										
R = Readab	le bit	W = Writable b	bit	U = Unimpler	mented bit, read	1 as '0'				
-n = Value a	t POR	'1' = Bit is set		0' = Bit is cleared x = Bit is unknown						
bit 15-9	Unimplemen	ted: Read as '0	3							
bit 8	ADDMAEN: A	ADC1 DMA Ena	ıble bit							
				0	ster for transfer ADC1BUFF reg	0				
bit 7-3	Unimplemen	ted: Read as '0	,							
bit 2-0	DMABL<2:0>	Selects Numb	per of DMA B	uffer Locations	per Analog Inpu	ut bits				
	110 = Allocat 101 = Allocat 100 = Allocat 011 = Allocat 010 = Allocat 001 = Allocat	es 128 words of es 64 words of 1 es 32 words of 1 es 16 words of 1 es 8 words of b es 4 words of b es 2 words of b es 1 word of bu	buffer to each buffer to each buffer to each uffer to each uffer to each a uffer to each a	analog input analog input analog input analog input analog input analog input analog input						

## REGISTER 23-4: AD1CON4: ADC1 CONTROL REGISTER 4

# dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

## REGISTER 24-12: PTGQPTR: PTG STEP QUEUE POINTER REGISTER<sup>(1)</sup>

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—		_	—
bit 15							bit 8
U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_					PTGQPTR<4:0	>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit,	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 Unimplemented: Read as '0'

bit 4-0 **PTGQPTR<4:0>:** PTG Step Queue Pointer Register bits This register points to the currently active Step command in the Step queue.

**Note 1:** This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

## **REGISTER 24-13: PTGQUEX: PTG STEP QUEUE REGISTER x (x = 0-7)**<sup>(1,3)</sup>

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			STEP(2x +	- 1)<7:0> <b>(2)</b>			
bit 15							bit 8
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
STEP(2x)<7:0> <sup>(2)</sup>								
bit 7								

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit,	read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8	STEP(2x + 1)<7:0>: PTG Step Queue Pointer Register bits <sup>(2)</sup>
	A queue location for storage of the STEP(2x + 1) command byte.
bit 7-0	STEP(2x)<7:0>: PTG Step Queue Pointer Register bits <sup>(2)</sup>
	A queue location for storage of the STEP(2x) command byte.

- **Note 1:** This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).
  - 2: Refer to Table 24-1 for the Step command encoding.

**3:** The Step registers maintain their values on any type of Reset.

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0			
CON	COE <sup>(2)</sup>	CPOL	_	—	OPMODE	CEVT	COUT			
bit 15							bit 8			
R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0			
EVPOL1	EVPOL0	—	CREF <sup>(1)</sup>	_	—	CCH1 <sup>(1)</sup>	CCH0 <sup>(1)</sup>			
bit 7							bit (			
Legend:										
R = Readabl	e bit	W = Writable	bit	U = Unimple	mented bit, read	as '0'				
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkr	nown			
bit 15	CON: Op Am	p/Comparator	Enable bit							
		comparator is e								
		comparator is d								
bit 14		arator Output Ei								
		tor output is pre		CxOUT pin						
	-	tor output is int	-							
bit 13	•	CPOL: Comparator Output Polarity Select bit								
		1 = Comparator output is inverted								
	-	tor output is no								
bit 12-11	•	ted: Read as '								
bit 10	<b>OPMODE:</b> Op Amp/Comparator Operation Mode Select bit									
		perates as an o perates as a co								
bit 9	•	arator Event bi	•							
	1 = Compara		rding to the E	VPOL<1:0> s	ettings occurred	; disables futur	e triggers and			
		ator event did n								
bit 8	COUT: Comp	parator Output b	oit							
	When CPOL = 0 (non-inverted polarity):									
	1 = VIN + > VIN-									
	0 = VIN + < VI									
		= 1 (inverted p	olarity):							
	1 = VIN + < VI									
	0 = VIN + > VI	N-								

#### **REGISTER 25-2:** CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2 OR 3)

- Note 1: Inputs that are selected and not available will be tied to Vss. See the "Pin Diagrams" section for available inputs for each package.
  - 2: This output is not available when OPMODE (CMxCON<10>) = 1.

## 27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the dsPIC33EPXXXGP50X. dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a То comprehensive reference source. complement the information in this data sheet, refer to the related section of the "dsPIC33/PIC24 Familv Reference Manual', which is available from the Microchip web site (www.microchip.com).

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard<sup>™</sup> Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming<sup>™</sup> (ICSP<sup>™</sup>)
- In-Circuit Emulation

## 27.1 Configuration Bits

In dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

Note:	Configuration data is reloaded on all types
	of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '1111 1111 1111 1111 1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

**Note:** Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

DC CHARACTERISTICS			$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$				
Parameter No.	Тур.	Max.	Units		Conditions		
Idle Current (III	dle) <sup>(1)</sup>						
DC40d	3	8	mA	-40°C			
DC40a	3	8	mA	+25°C	- 3.3V	10 MIPS	
DC40b	3	8	mA	+85°C	3.3V	10 101195	
DC40c	3	8	mA	+125°C	]		
DC42d	6	12	mA	-40°C			
DC42a	6	12	mA	+25°C	3.3V	20 MIPS	
DC42b	6	12	mA	+85°C	3.3V	20 1011 3	
DC42c	6	12	mA	+125°C			
DC44d	11	18	mA	-40°C		40 MIPS	
DC44a	11	18	mA	+25°C	3.3V		
DC44b	11	18	mA	+85°C	5.50	40 1011-3	
DC44c	11	18	mA	+125°C			
DC45d	17	27	mA	-40°C			
DC45a	17	27	mA	+25°C	- 3.3V	60 MIPS	
DC45b	17	27	mA	+85°C	3.3V		
DC45c	17	27	mA	+125°C	]		
DC46d	20	35	mA	-40°C			
DC46a	20	35	mA	+25°C	3.3V	70 MIPS	
DC46b	20	35	mA	+85°C	]		

#### TABLE 30-7: DC CHARACTERISTICS: IDLE CURRENT (lidle)

**Note 1:** Base Idle current (IIDLE) is measured as follows:

• CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)

- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to Vss
- $\overline{\text{MCLR}}$  = VDD, WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- The NVMSIDL bit (NVMCON<12>) = 1 (i.e., Flash regulator is set to standby while the device is in Idle mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

АС СНА	ARACTERIS	TICS		$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$				
Param No.	Symbol	Charao	cteristic <sup>(1)</sup>	Min.	Тур.	Max.	Units	Conditions
TB10	TtxH	TxCK High Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N	_	_	ns	Must also meet Parameter TB15, N = prescale value (1, 8, 64, 256)
TB11	TtxL	TxCK Low Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N	_		ns	Must also meet Parameter TB15, N = prescale value (1, 8, 64, 256)
TB15	TtxP	TxCK Input Period	Synchronous mode	Greater of: 40 or (2 Tcy + 40)/N	—	—	ns	N = prescale value (1, 8, 64, 256)
TB20	TCKEXTMRL	Delay from Clock Edge Increment	External TxCK to Timer	0.75 Tcy + 40	—	1.75 Tcy + 40	ns	

<b>TABLE 30-24</b>	TIMER2 AND TIM	IER4 (TYPE B TIMER	ER) EXTERNAL CLOCK TIMING REQUIREMENTS	j.
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Note 1: These parameters are characterized, but are not tested in manufacturing.

#### TABLE 30-25: TIMER3 AND TIMER5 (TYPE C TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

АС СНА	RACTERIST	TICS		$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^\circ C \leq TA \leq +85^\circ C \mbox{ for Industrial} \\ & -40^\circ C \leq TA \leq +125^\circ C \mbox{ for Extended} \end{array}$				
Param No.	Symbol	Charac	teristic <sup>(1)</sup>	Min.	Тур.	Max.	Units	Conditions
TC10	TtxH	TxCK High Time	Synchronous	Tcy + 20			ns	Must also meet Parameter TC15
TC11	TtxL	TxCK Low Time	Synchronous	Тсү + 20	_	—	ns	Must also meet Parameter TC15
TC15	TtxP	TxCK Input Period	Synchronous, with prescaler	2 Tcy + 40	—	_	ns	N = prescale value (1, 8, 64, 256)
TC20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 Tcy + 40	_	1.75 Tcy + 40	ns	

**Note 1:** These parameters are characterized, but are not tested in manufacturing.

## 33.0 PACKAGING INFORMATION

#### 33.1 Package Marking Information

#### 28-Lead SPDIP



#### 28-Lead SOIC (.300")



28-Lead SSOP



Example dsPIC33EP64GP 502-I/SP@3 1310017

## Example



#### Example



28-Lead QFN-S (6x6x0.9 mm)



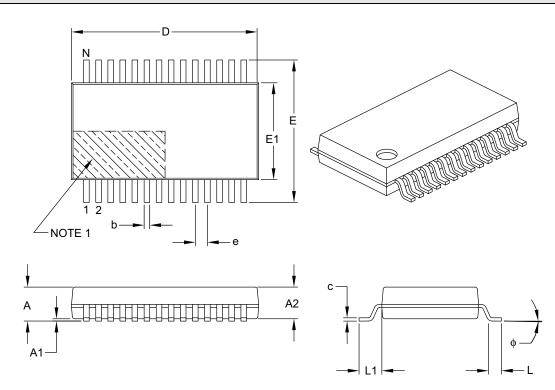
Example



Legend	: XXX Y YY WW NNN @3 *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.				
	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.					

#### 28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units			6	
Dime	ension Limits	MIN	NOM	MAX	
Number of Pins	N		28		
Pitch	е		0.65 BSC		
Overall Height	A	-	-	2.00	
Molded Package Thickness	A2	1.65	1.75	1.85	
Standoff	A1	0.05	-	-	
Overall Width	E	7.40	7.80	8.20	
Molded Package Width	E1	5.00	5.30	5.60	
Overall Length	D	9.90	10.20	10.50	
Foot Length	L	0.55	0.75	0.95	
Footprint	L1	1.25 REF			
Lead Thickness	С	0.09	-	0.25	
Foot Angle	ф	0°	4°	8°	
Lead Width	b	0.22	-	0.38	

#### Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.

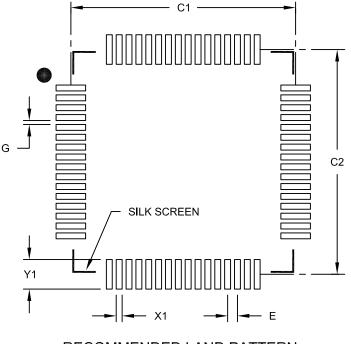
- 3. Dimensioning and tolerancing per ASME Y14.5M.
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units				
Dimensio	n Limits	MIN	NOM	MAX	
Contact Pitch	E		0.50 BSC		
Contact Pad Spacing	C1		11.40		
Contact Pad Spacing	C2		11.40		
Contact Pad Width (X64)	X1			0.30	
Contact Pad Length (X64)	Y1			1.50	
Distance Between Pads	G	0.20			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

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